

IN THE CLAIMS:

Claim 1 (Currently amended): A method of peeling a semiconductor chip, comprising the steps of:

peeling a semiconductor chip adhered to a tape from said tape by a peeling device including a plurality of ~~annular~~ displaceable contact members arranged in an order from an outer circumferential position to a central position all being housed inside a stationary contact member, wherein the plurality of displaceable ~~annular~~ contact members are operated and displaced relative to each other so that the semiconductor chip is successively peeled off from the tape from the outer circumferential position thereof toward the central position.

Claim 2 (Currently amended): The method of peeling a semiconductor chip according to claim 1, wherein the plurality of ~~annular~~ displaceable contact members are simultaneously moved, and then, the an outermost ~~annular~~ displaceable contact member in the plurality of ~~annular~~ displaceable contact members is stopped and the remaining ~~annular~~ displaceable contact members are further moved simultaneously.

Claim 3 (Currently amended): A device for peeling a semiconductor chip adhered to a tape off from said tape, comprising:

a plurality of ~~annular~~ displaceable contact members arranged in an order from an outer circumferential position to a central position all being housed inside a stationary contact member;

and

an operation device for operating the plurality of displaceable annular contact members to displace them relative to each other so that the semiconductor chip is successively peeled, from the tape, from the outer circumferential position thereof to the central position.

Claim 4 (Currently amended): The device for peeling a semiconductor chip according to claim 3, wherein the operation device includes a cam for operating the plurality of ~~annular~~ displaceable contact members.

Claim 5 (Currently amended): The device for peeling a semiconductor chip according to claim 3, further comprising a frame defining a vacuum chamber therein, a top plate arranged on said frame and having an opening, and a suction device arranged above said frame, said ~~annular~~ displaceable contact members being arranged in said frame.

Claim 6 (Currently amended): A method of peeling a semiconductor chip, comprising the steps of:

peeling a semiconductor chip adhered to a tape from said tape by a peeling device including a plurality of ~~annular~~ displaceable contact members arranged one after another from the outside to the inside, wherein the plurality of ~~annular~~ displaceable contact members are operated so that the semiconductor chip is successively peeled off from the tape from an outer circumferential portion thereof toward a central portion thereof; and

wherein the plurality of ~~annular~~ displaceable contact members are simultaneously moved, and then, the outermost ~~annular~~ displaceable contact member in the plurality of ~~annular~~ displaceable contact members is stopped and the remaining ~~annular~~ displaceable contact members are further moved simultaneously.